1. Record Nr. UNINA990000497380403321

Autore	Bobbio, Scipione <1941-2000>
Titolo	Elettrotecnica / Bobbio, Greco
Pubbl/distr/stampa	Napoli : CUEN, stampa 1982
Descrizione fisica	156 p. : ill. ; 24 cm
Altri autori (Persone)	Greco, Oreste
Disciplina	621.3
Locazione	DINEL
Collocazione	10 C I 296 10 C I 297
Lingua di pubblicazione	Italiano
Formato	Materiale a stampa
Livello bibliografico	Monografia

2. Record Nr. UNINA9910783237303321

Titolo	The media in Europe [[electronic resource]] : the Euromedia handbook : Central and Eastern European / / edited by Mary Kelly, Gianpietro Mazzoleni, Denis McQuail
Pubbl/distr/stampa	London, : SAGE, c2004
ISBN	0-7619-4132-0 1-280-36861-6 9786610368617 1-4129-3260-2
Edizione	[3rd ed.]
Descrizione fisica	1 online resource (vii, 274 p.)
Altri autori (Persone)	KellyMary <1944-> MazzoleniGianpietro McQuailDenis
Disciplina	302.230943
Soggetti	Mass media - Europe, Central Mass media - Europe, Eastern
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa

Livello bibliografico	Monografia
Note generali	Enl. ed. of: The media in Western Europe. 2nd ed. 1997.
Nota di bibliografia	Includes bibliographical references (p. 274).
Nota di contenuto	Cover; Contents; Notes on contributors; Acknowledgements; How to use this book; Introduction; Chapter 1 - Austria; Chapter 2 - Belgium; Chapter 3 - The Czech Republic; Chapter 4 - Denmark; Chapter 5 - Finland; Chapter 6 - France; Chapter 7 - Germany; Chapter 8 - Greece; Chapter 9 - Hungary; Chapter 10 - Ireland; Chapter 11 - Italy; Chapter 12 - Luxembourg; Chapter 13 - The Netherlands; Chapter 14 - Norway; Chapter 15 - Poland; Chapter 16 - Portugal; Chapter 17 - Russia; Chapter 18 - Slovakia; Chapter 19 - Slovenia; Chapter 20 - Spain; Chapter 21 - Sweden; Chapter 22 - Switzerland Chapter 23 - The United Kingdom
Sommario/riassunto	Completely rewritten, the 3rd edition of this successful guide to European media systems has also been expanded to include Central and Eastern Europe.

3.

Record Nr.	UNINA9910366578603321
Autore	Chen Zengtao
Titolo	Advanced Thermal Stress Analysis of Smart Materials and Structures / / by Zengtao Chen, Abdolhamid Akbarzadeh
Pubbl/distr/stampa	Cham : , : Springer International Publishing : , : Imprint : Springer, , 2020
ISBN	3-030-25201-9
Edizione	[1st ed. 2020.]
Descrizione fisica	1 online resource (X, 304 p. 104 illus., 44 illus. in color.)
Collana	Structural Integrity, , 2522-560X ; ; 10
Disciplina	531 620.11296
Soggetti	Mechanics Mechanics, Applied Materials science Mathematical models Solid Mechanics Characterization and Evaluation of Materials Mathematical Modeling and Industrial Mathematics
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa

Livello bibliografico	Monografia
Nota di contenuto	Heat conduction and moisture diffusion theories -- Basic Problems of Non-Fourier Heat Conduction -- Multiphysics of smart materials and structures -- Coupled thermal stresses in advanced and smart materials -- Thermal Fracture of Advanced Materials based on Fourier Heat Conduction -- Advanced thermal fracture analysis based on non-Fourier heat conduction models -- Future Perspectives.
Sommario/riassunto	This is the first single volume monograph that systematically summarizes the recent progress in using non-Fourier heat conduction theories to deal with the multiphysical behaviour of smart materials and structures. The book contains six chapters and starts with a brief introduction to Fourier and non-Fourier heat conduction theories. Non-Fourier heat conduction theories include Cattaneo-Vernotte, dual-phase-lag (DPL), three-phase-lag (TPL), fractional phase-lag, and nonlocal phase-lag heat theories. Then, the fundamentals of thermal wave characteristics are introduced through reviewing the methods for solving non-Fourier heat conduction theories and by presenting transient heat transport in representative homogeneous and advanced heterogeneous materials. The book provides the fundamentals of smart materials and structures, including the background, application, and governing equations. In particular, functionally-graded smart structures made of piezoelectric, piezomagnetic, and magnetoelectroelastic materials are introduced as they represent the recent development in the industry. A series of uncoupled thermal stress analyses on one-dimensional structures are also included. The volume ends with coupled thermal stress analyses of one-dimensional homogenous and heterogeneous smart piezoelectric structures considering different coupled thermopiezoelectric theories. Last but not least, fracture behavior of smart structures under thermal disturbance is investigated and the authors propose directions for future research on the topic of multiphysical analysis of smart materials. .